



# 2.0A SBR<sup>®</sup> SURFACE MOUNT SUPER BARRIER RECTIFIER PowerDI<sup>®</sup> 123

#### **Features**

- Low Forward Voltage Drop
- Low Leakage Current
- Superior Reverse Avalanche Capability
- Excellent High Temperature Stability
- Patented Interlocking Clip Design for High Surge Current Capacity
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- ±16KV ESD Protection (HBM, 3B)
- ±25KV ESD Protection (IEC61000-4-2 Level 4, Air Discharge)
- Lead Free Finish, RoHS Compliant (Note 1)
- "Green" Molding Compound (No Br, Sb)
- Qualified to AEC-Q 101 Standards for High Reliability

#### Mechanical Data

- Case: PowerDI<sup>®</sup>123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity Indicator: Cathode Band
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.018 grams (approximate)



Top View

### **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$		
Working Peak Reverse Voltage	$V_{RWM}$	40	V
DC Blocking Voltage	$V_{RM}$		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	28	V
Average Rectified Output Current (See Figure 1)	Io	2.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	50	А
Repetitive Peak Avalanche Power (1μs, 25°C)	P <sub>ARM</sub>	6,000	W

#### Thermal Characteristics

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Thermal Resistance Junction to Soldering (Note 2) Thermal Resistance Junction to Ambient (Note 3) Thermal Resistance Junction to Ambient (Note 4)	$egin{array}{c} {\sf R}_{ heta {\sf JA}} \ {\sf R}_{ heta {\sf JA}} \end{array}$	5 180 115	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

Notes:

- 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
- 2. Theoretical R<sub>nJS</sub> calculated from the top center of the die straight down to the PCB cathode tab solder junction.
- 3. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf.

4. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf.

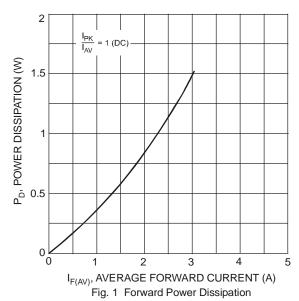


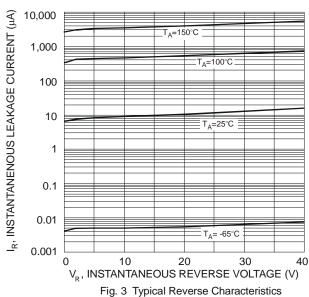
### **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

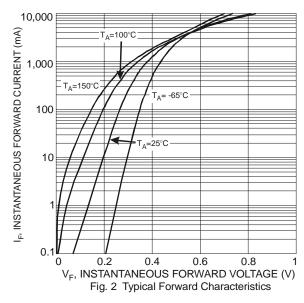
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	40	-	-	V	$I_R = 100\mu A$
	V <sub>F</sub>	ı	0.265	0.315		$I_F = 0.1A, T_J = 25^{\circ}C$
		-	0.38	0.43		$I_F = 1.0A, T_J = 25^{\circ}C$
Forward Voltage Drop		ı	0.45	0.50	V	$I_F = 2.0A, T_J = 25^{\circ}C$
Forward Voltage Drop		-	0.17	0.22		$I_F = 0.1A, T_J = 125^{\circ}C$
		-	0.325	0.375		$I_F = 1.0A, T_J = 125$ °C
		ı	0.42	0.47		$I_F = 2.0A, T_J = 125^{\circ}C$
	I <sub>R</sub>	-	8	40	μΑ	$V_R = 5V, T_J = 25^{\circ}C$
Lookogo Current (Noto E)		ı	16	100	μA	$V_R = 40V, T_J = 25^{\circ}C$
Leakage Current (Note 5)		-	1.3	8	mA	$V_R = 5V, T_J = 125^{\circ}C$
		-	2.1	10	mA	$V_R = 40V, T_J = 125^{\circ}C$

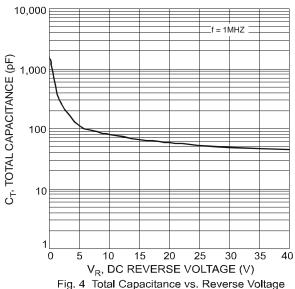
Notes:

5. Short duration pulse test used to minimize self-heating effect.

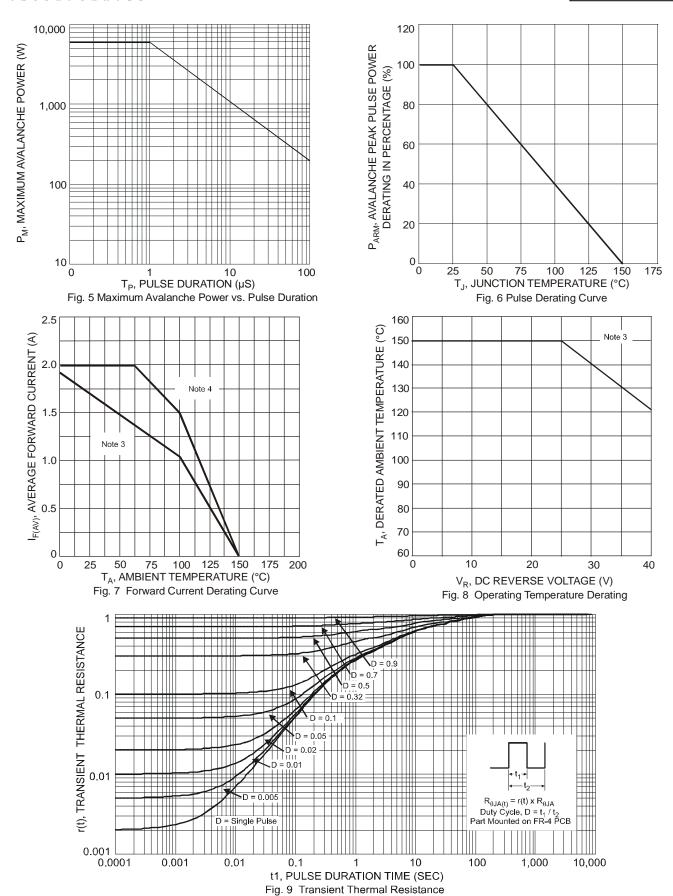












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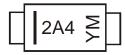


## Ordering Information (Note 6)

Part Number	Case	Packaging	
SBR2A40P1-7	PowerDI <sup>®</sup> 123	3000/Tape & Reel	

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Marking Information**

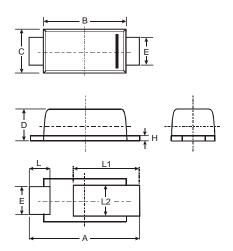


2A4 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: T = 2006) M = Month (ex: 9 = September)

Date Code Key

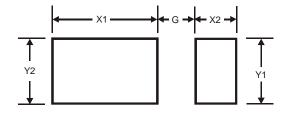
Date Code Ney												
Year	2006	2007	20	08	2009	2010	2011	2012	20	013	2014	2015
Code	Т	U	\	/	W	Χ	Υ	Z		A	В	С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

# **Package Outline Dimensions**



PowerDI <sup>®</sup> 123					
Dim	Min	Max	Тур		
Α	3.50	3.90	3.70		
В	2.60	3.00	2.80		
С	1.63	1.93	1.78		
D	0.93	1.00	0.98		
Е	0.85	1.25	1.00		
H	0.15	0.25	0.20		
<b>L</b> 0.55 0.75 0.65					
L1	1.80	2.20	2.00		
L2	0.95	1.25	1.10		
All Dimensions in mm					

# Suggested Pad Layout



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4



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